%.%% /012304%506754%%

D	2017-5				
E	2021-1-27	4/7	e0.5-0.7 0.5-0.8 5 7		

2.0A

%%.%% 'D37@?>0% 9E2F?F%/9>2;<3G(9H I J%

%

Parameter	Symbol	Rating					Unit
		MB24F	MB26F	MB28F	MB210F	MB220F	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	40	60	80	100	200	V
Maximum RMS Voltage	V_{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V_{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2.0					A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50		40			A
Typical Junction Capacitance[1)]	C_j	220	80				pF
Typical Thermal Resistance[2)]	$R_{\theta JA}$	75					/W
Operating Junction Temperature Range	T_j	-55~+125					
Storage Temperature Range	T_{stg}	-55~+150					

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×(5×5mm^2) copper pad.

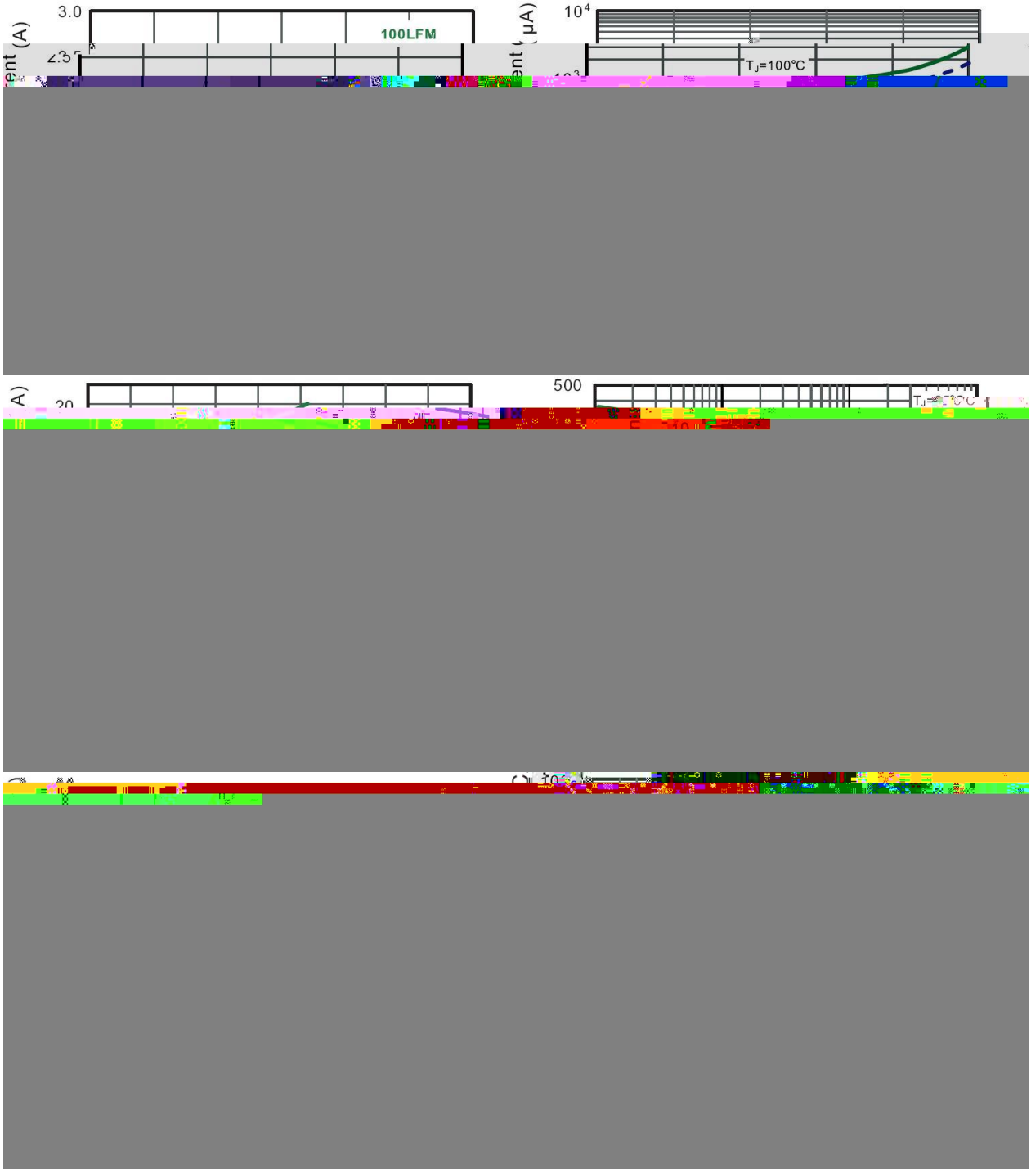
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%%.%% +@06>5269@%BK9596>0523>263G(9H I J%

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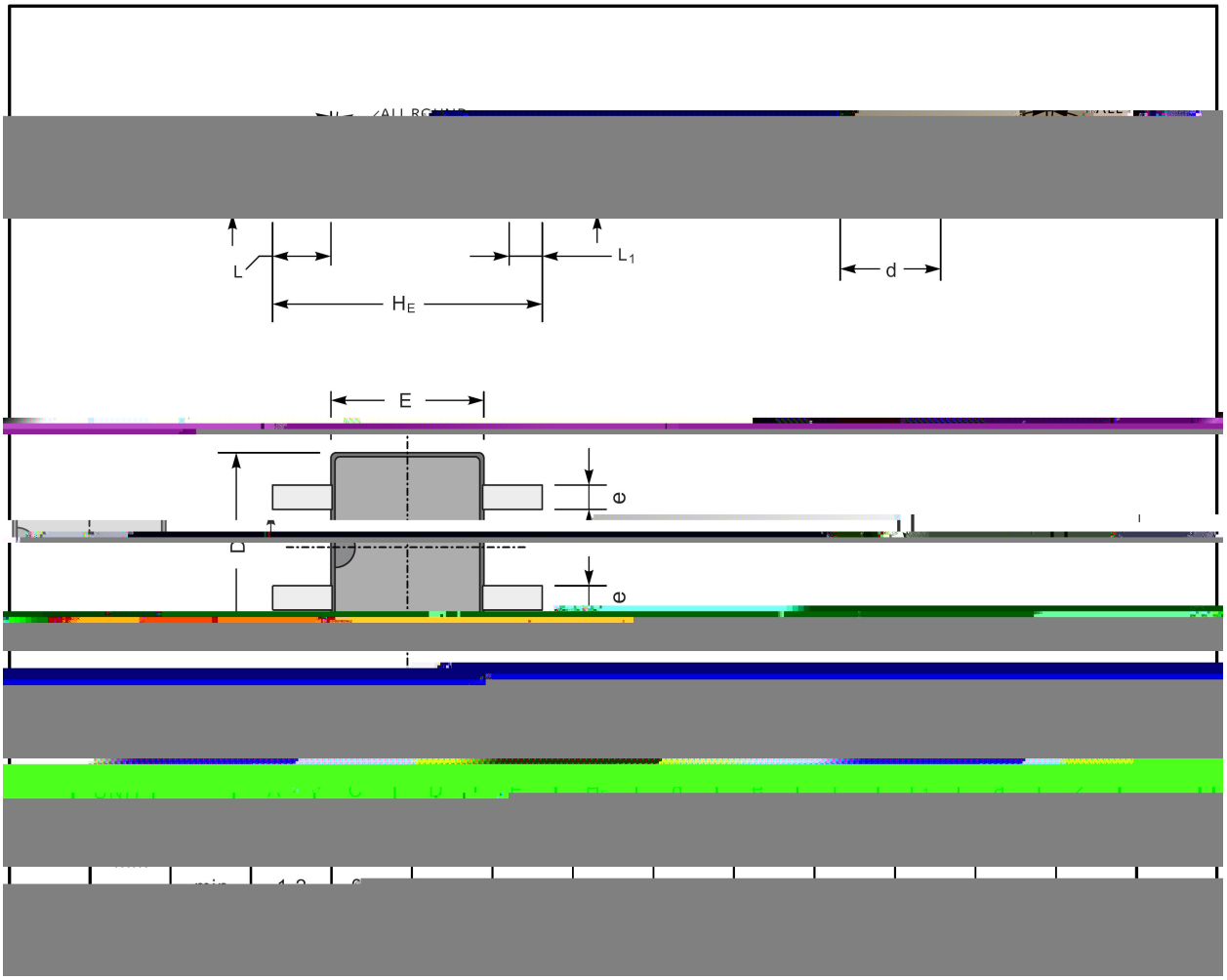
Parameter	Symbol	Test Conditions	数值 Rating					Unit
			MB24F	MB26F	MB28F	MB210F	MB220F	
Max Instantaneous Forward Voltage	V_F	I_F=2.0A	0.55	0.70	0.85			V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25℃	0.5			0.3		mA
		T_a=100℃	10			5.0		mA

% % .% % +@06>5269@%BK9596>0523>26%B?510%

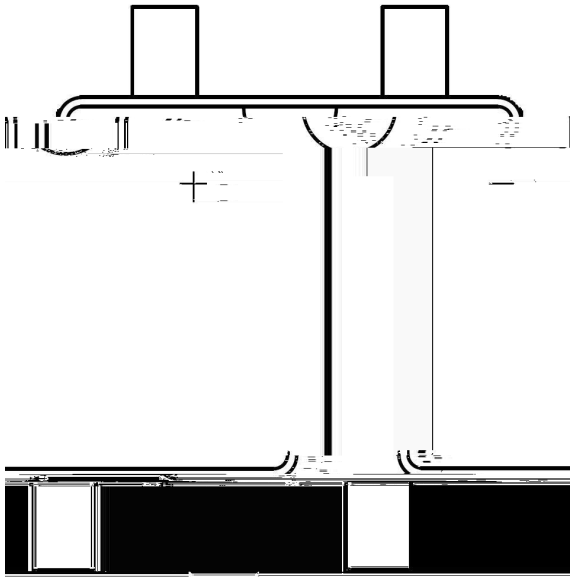


%%.%% C96 : 9<0%&2 F 0 ; 327 ; 3%

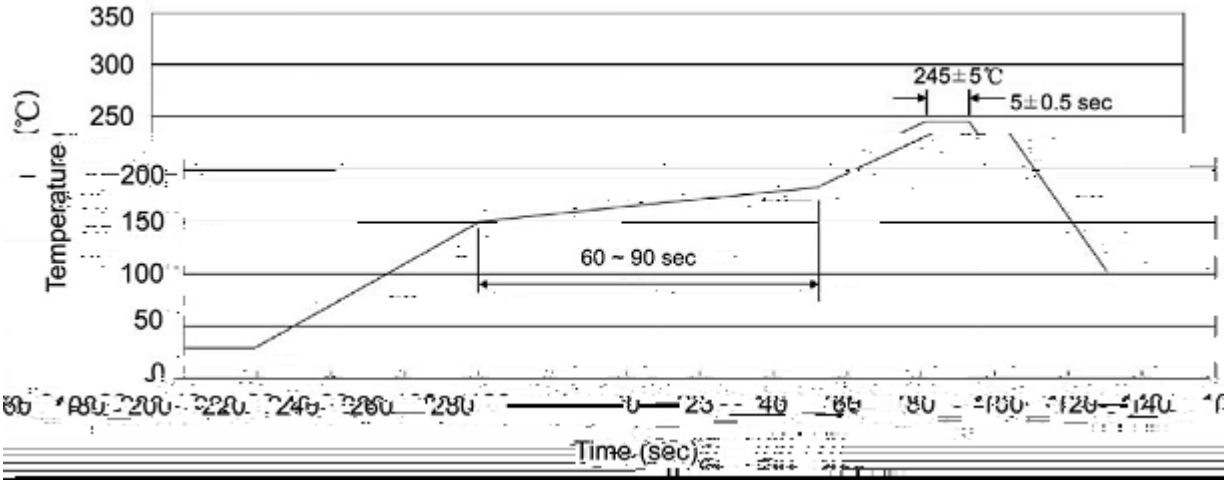
MBF



%%.%% 95:2;<%M;3>5?6>27;3%



G J%%.%% Temperature Profile for IR Reflow Soldering(Pb-Free)



			Note:
1	25 150	60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2	245±5	5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2 10 /sec.	3. Cooling Speed: 2~10 /sec.

%%.%%% /0323>9;60%>7%)7@4052;<%*09>%(03>%B7;42>27;3%

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

%%.%%C96:9<2;<%)C+B%

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱